

date 08/05/2022

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MODEL: HSB24-252510 | DESCRIPTION: HEAT SINK

FEATURES

- BGA design
- small footprint
- top mount
- · aluminum alloy





thermal resistance¹ **MODEL** power dissipation¹ @ 75°C ∆T, nat @ 1 W, @ 1W, @ 1 W, @ 75°C ∆T, nat 400 LFM conv (°C/W) nat conv 200 LFM conv (°C/W) (°C/W) $(^{\circ}C/W)$ (W) HSB24-252510 18.10 21.3 6.5 4.0 4.14

Note: 1. S

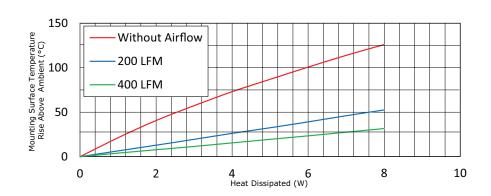
1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	21.3	6.5	4.0
2	40.6	12.9	7.8
3	57.3	19.5	11.5
4	73.0	26.2	15.5
5	86.9	32.5	19.5
6	100.6	39.1	23.4
7	113.8	46.0	27.5
8	125.9	52.5	31.6



Ta: ambient temperature

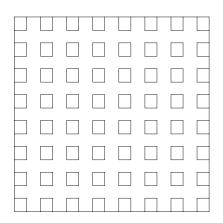


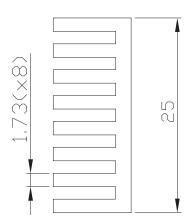
MECHANICAL DRAWING

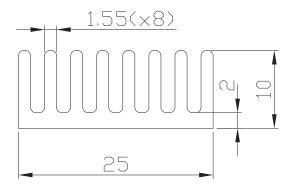
units: mm

tolerance: ±0.5 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	8.8 g







REVISION HISTORY

rev.	description	date
1.0	initial release	04/22/2022
1.01	logo, datasheet style update	08/05/2022

The revision history provided is for informational purposes only and is believed to be accurate.



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